MA3S132DG, MA3S132EG

Silicon epitaxial planar type

For switching circuits

■ Features

- Short reverse recovery time t_{rr}
- Small terminal capacitance C_t
- Two isolated elements contained in one package, allowing highdensity mounting

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter		Symbol	Rating	Unit
Reverse voltage		V_R	80	V
Maximum peak reverse voltage		V_{RM}	80	V
Forward current	Single	I_F	100	mA
	Double		150	
Peak forward	Single	I_{FM}	225	mA
current	Double		340	
Non-repetitive peak	Single	I_{FSM}	500	mA
forward surge current *	Double		750	
Junction temperature		T _j	150	°C
Storage temperature		T_{stg}	-55 to +150	°C

Note) *: t = 1 s

Package

Code SSMini3-F3

• Pin Name

MA3S132DG MA3S132EG

1: Cathode 1 1: Anode 1 2: Cathode 2 2: Anode 2 3: Anode 3: Cathode

■ Marking Symbol

MA3S132DG: MO MA3S132EG: MU

■ Internal Connection



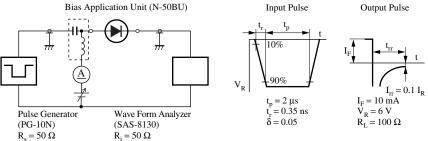


■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

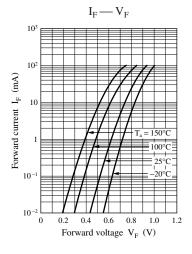
Parameter		Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage		V_{F}	$I_F = 100 \text{ mA}$			1.2	V
Reverse voltage		V _R	$I_R = 100 \mu A$	80			V
Reverse current		I_R	$V_R = 75 \text{ V}$			100	nA
Terminal capacitance	MA3S132DG	C _t	$V_R = 0 V, f = 1 MHz$			15	pF
	MA3S132EG					2	
Reverse recovery time *	MA3S132DG	t _{rr}	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}$			10	ns
	MA3S132EG		$I_{rr} = 0.1 \ I_R \ , \ R_L = 100 \ \Omega$			3	

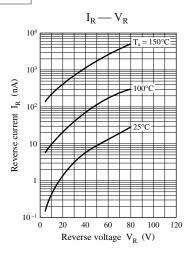
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

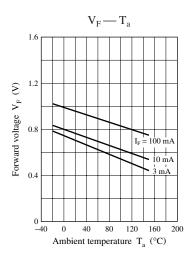
- 2. Absolute frequency of input and output is 100 MHz.
- 3. *: t_{rr} measurement circuit

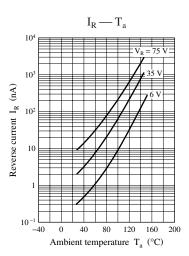


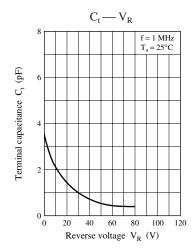
Characteristics charts of MA3S132DG

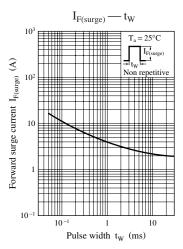






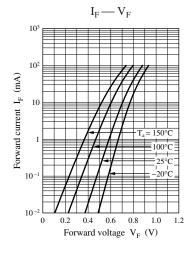


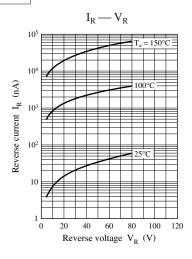


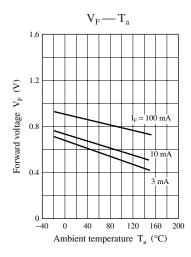


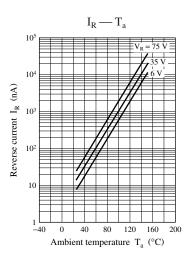
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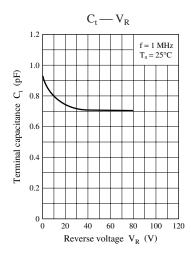
Characteristics charts of MA3S132EG

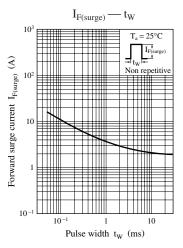








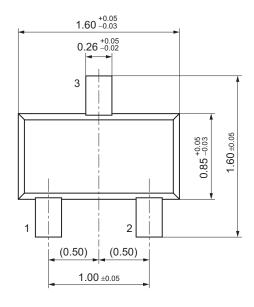


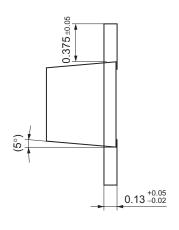


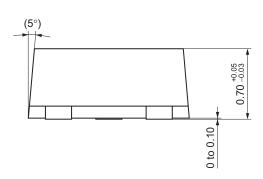
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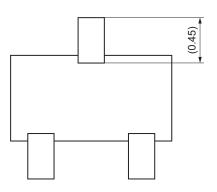
Unit: mm

SSMini3-F3









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